

ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES®

## **Material Composition Declaration**

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>

Form Type\*
Distribute

Declaration Class\* Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infomation

Supplier Information					
Company Name *	Company Unique ID	Unique ID Authority	Response Date*		
Fairchild Semiconductor	00-489-5751	Dun & Bradstreet	Sat, Feb 22, 2014 04:00 AM		
Contact Name *	Title - Contact	Phone - Contact *	Email - Contact *		
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com		
Authorized Representative *	Title - Representative	Phone - Representative *	Email - Representative *		
David Lancaster	Product Ecology	801-562-7455	david.lancaster@fairchildsemi.com		

п	Requester Item Number	Mfr Iter	n Number	Mfr Item Name		Effective Date	Version M		fanufacturing Site	Weight*	UOM	Unit Type	
	QSE113	QS	E113	SIDELOOKER DIODE				SUBCONTRACTOR		0.144016	g	Each	
Ī	Manufacturing Process Information												
	Terminal Finish	Base Alloy	J-STD-0	020 MSL Rating	Peak Process Body Ten		dy Tempera	ture	Max Time at Peak Temperature		No Re	No Reflow cycles	
	Matte Tin (Sn)	Other	Not	Applicable		C		seco	Not A	Not Applicable			

<sup>\*</sup> Required Field

## **RoHS Material Composition Declaration**

Declaration Type \* Custom

RoHS Directive 2011/65/EU **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.

The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.

Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.

RoHS Declaration \*

1 - Item(s) does not contain RoHS restricted substances per the definition above

Supplier Acceptance \* Accepted

Exemptions: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

Exemption List Version EL-2011/534/EU

None

**Declaration Signature** 

Supplier Signature

DAVID LANCASTER - PRODUCT ECOLOGY MANAGER

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## **Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name SIDELOOKER DIODE

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM
Chip	Other inorganic materials	0.650	Supplier		Silicon	0.650	7440-21-3	4513
Die Attach	Other Organic Materials	0.610	Supplier		Acrylic Resin	0.092	54208-63-8	635
			Supplier		Silica, vitreous	0.092	60676-86-0	635
			Supplier		Silver	0.427	7440-22-4	2965
Encapsulation	Thermoplastics	20.000	Supplier		Acrylic Resin	10.000	54208-63-8	69437
			Supplier		Epoxy Resin	10.000	29690-82-2	69437
Lead Frame	Other Ferrous alloys, non-stainless steels	90.600	Supplier		Carbon	3.624	7440-44-0	25164
			Supplier		Iron	82.174	7439-89-6	570591
			Supplier		Manganese	2.084	7439-96-5	14469
			Supplier		Phosphorus	1.540	7723-14-0	10695
			Supplier		Silver	0.453	7440-22-4	3145
			Supplier		Sulfur	0.725	7704-34-9	5033
Plating	Other Nonferrous metals & alloys	30.016	Supplier		Copper	0.216	7440-50-8	1500
			Supplier		Tin	29.800	7440-31-5	206921
Wire Bond	Precious metals	2.140	Supplier		Gold	2.140	7440-57-5	14859